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- (71) Applicant (for all designated States except US): HEWLETT-PACKARD COMPANY [US/US]; Legal Dept., 3000 Hanover Street, Palo Alto, CA 94304 (US).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): COLFER, Paul [IE/IE]; 95 Clonmich Wood, Tullamore, Co. Offaly (IE). BYRNE, Lorraine [IE/IE]; 37 Warrenstown Drive, Blanchardstown 15, Dublin (IE). CAHILL, Eugene [IE/IE]; Firpark, Crossakiel, Kells, Co. Meath (IE). KEENAN, Philip [IE/IE]; 9 Griffeen Glen Road, Griffeen Valley, Lucan, Co. Dublin (IE). STOBIE, Niall [IE/IE]; 52 St. Brendans Avenue, Coolock 5, Dublin (IE).

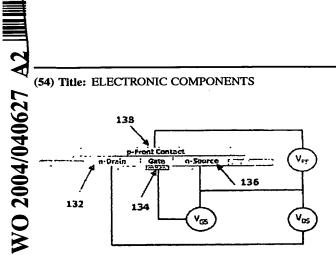
- (74) Agent: ORSI, Alessandro; Hewlett-Packard Española, S.L., Legal Dept., Avda. Graells 501, 08190 Sant Cugat del Valles (ES).
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(54) Title: ELECTRONIC COMPONENTS



(57) Abstract: A method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing inorganic semi-conducting nanoparticles and dopant on a substrate, the nanoparticles being a group four element such as silicon or germanium; fusing the nanoparticles by heating to form a continuous layer; and subsequently; and, recrystallising the layer.